

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
9 September 2005 (09.09.2005)

PCT

(10) International Publication Number
WO 2005/083749 A1

(51) International Patent Classification⁷: H01L 21/00,
G01R 31/26, G09G 3/00

(21) International Application Number:
PCT/US2004/043202

(22) International Filing Date:
21 December 2004 (21.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/778,982 12 February 2004 (12.02.2004) US

(71) Applicant (for all designated States except US): AP-
PLIED MATERIALS, INC. [US/US]; 3050 Bowers Ave,
Santa Clara, CA 95054 (US).

(72) Inventors; and

(75) Inventors/Applicants (for US only): KURITA, Shinichi
[JP/US]; 3532 Rollingside Drive, San Jose, CA 95148
(US). BEER, Emanuel [US/US]; 7162 Via Vico, San
Jose, 95129 (US). NGUYEN, Hung, T. [US/US]; 4399

MacBeth Circle, Fremont, CA 94555 (US). JOHNSTON,
Benjamin [US/US]; 20701 Locust Drive, Los Gatos, CA
95033 (US). ABOUD, Fayez, E. [US/US]; 1859 Zenato
Place, Pleasanton, CA 94566 (US).

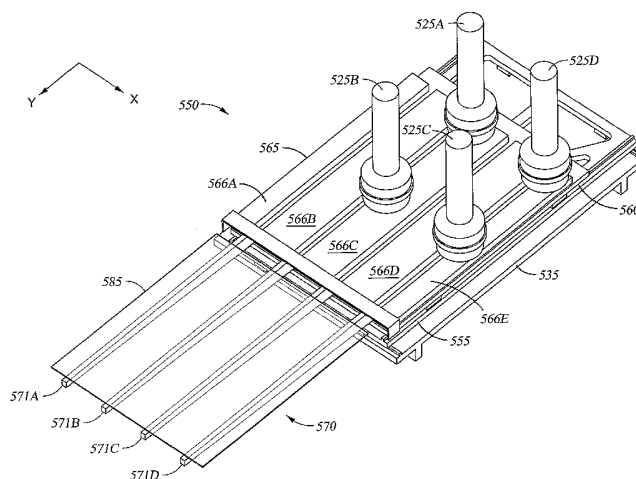
(74) Agents: PATTERSON, B., Todd et al.; Moser, Patterson
& Sheridan, LLP, 3040 Post Oak Blvd., Suite 1500, Hous-
ton, TX 77056-6582 (US).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ,
TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA,
ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,
GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

[Continued on next page]

(54) Title: TEST SYSTEM WITH INTEGRATED SUBSTRATE TRANSFER MODULE



(57) Abstract: An integrated system (100) for supporting and transferring a substrate is provided. In one aspect, the integrated system (100) includes a transfer chamber (500) having a substrate table (550) disposed therein. The substrate table (550) is capable of moving a substrate (585) within the testing chamber (500) in both horizontal and vertical directions. The substrate table (550) includes a first stage moveable (535) in a first dimension, a second stage (555) moveable in a second dimension, and a third stage (565) moveable in a third dimension. Each stage (535, 555, 565) moves independently in its respective dimension. The system (100) can also include a load lock chamber (400) disposed adjacent a first side of the testing chamber (500), and a prober storage assembly (200) disposed beneath the testing chamber (500). A prober stack assembly (300) can be disposed adjacent a second side of the testing chamber (500) and arranged to transfer one or more probes (205) between the prober storage assembly (200) and the testing chamber (500). Further, one or more electron beam testing devices (525) can be disposed on an upper surface of the testing chamber (500).

WO 2005/083749 A1



FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO,
SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, ML, MR, NE, SN, TD, TG).

— *before the expiration of the time limit for amending the
claims and to be republished in the event of receipt of
amendments*

Published:

— *with international search report*

*For two-letter codes and other abbreviations, refer to the "Guid-
ance Notes on Codes and Abbreviations" appearing at the begin-
ning of each regular issue of the PCT Gazette.*

TEST SYSTEM WITH INTEGRATED SUBSTRATE TRANSFER MODULE

BACKGROUND OF THE INVENTION

Field of the Invention

[0001] Embodiments of the present invention generally relate to an integrated electron beam testing system for glass panel substrates.

Description of the Related Art

[0002] Active matrix liquid crystal displays (LCDs) are commonly used for applications such as computer and television monitors, cell phone displays, personal digital assistants (PDAs), and an increasing number of other devices. Generally, an active matrix LCD comprises two glass plates having a layer of liquid crystal materials sandwiched therebetween. One of the glass plates typically includes a conductive film disposed thereon. The other glass plate typically includes an array of thin film transistors (TFTs) coupled to an electrical power source. Each TFT may be switched on or off to generate an electrical field between a TFT and the conductive film. The electrical field changes the orientation of the liquid crystal material, creating a pattern on the LCD.

[0003] The demand for larger displays, increased production and lower manufacturing costs has created a need for new manufacturing systems that can accommodate larger substrate sizes. Current TFT LCD processing equipment is generally configured to accommodate substrates up to about 1.5 x 1.8 meters. However, processing equipment configured to accommodate substrate sizes up to and exceeding 1.9 x 2.2 meters is envisioned in the immediate future. Therefore, the size of the processing equipment as well as the process throughput time is a great concern to TFT LCD manufacturers, both from a financial standpoint and a design standpoint.

[0004] For quality control and profitability reasons, TFT LCD manufacturers are increasingly turning toward device testing to monitor and correct defects during

processing. Electron beam testing (EBT) can be used to monitor and troubleshoot defects during the manufacturing process, thereby increasing yield and reducing manufacturing costs. In a typical EBT process, TFT response is monitored to provide defect information. For example, EBT can be used to sense TFT voltages in response to a voltage applied across the TFT. Alternatively, a TFT may be driven by an electron beam and the resulting voltage generated by the TFT may be measured.

[0005] During testing, each TFT is positioned under an electron beam. This is accomplished by positioning a substrate on a table positioned below the beam and moving the table to sequentially position each TFT on the substrate below the electron beam test device.

[0006] As flat panels increase in size, so does the table and associated equipment used for the testing. Larger equipment requires more space, *i.e.*, a larger footprint per processing unit throughput, resulting in a higher cost of ownership. The large size of the equipment also increases the cost of shipping and may, in some cases, restrict the means and locales to which such equipment may be transported.

[0007] Therefore, there is a need for a compact testing system for flat panel displays that conserves clean room space and that can reliably position flat panels under an EBT device.

SUMMARY OF THE INVENTION

[0008] The present invention generally provides an integrated system for testing a substrate, including flat panel displays. The integrated system includes a substrate table. The substrate table is capable of moving a substrate within a testing chamber in horizontal and vertical directions. In one or more embodiments, the substrate table includes a first stage moveable in a first dimension, a second stage moveable in a second dimension, and a third stage moveable in a third dimension. Each stage moves independently in its respective dimension. In one or more embodiments described above or elsewhere herein, the system further

includes a load lock chamber disposed adjacent a first side of the testing chamber. In one or more embodiments described above or elsewhere herein, the system further includes a prober storage assembly disposed beneath the testing chamber. In one or more embodiments described above or elsewhere herein, a prober transfer assembly can be disposed adjacent a second side of the testing chamber and arranged to transfer one or more probes between the prober storage assembly and the testing chamber. In one or more embodiments described above or elsewhere herein, one or more testing devices can be disposed on an upper surface of the testing chamber. In one or more embodiments described above or elsewhere herein, one or more electron beam testing devices can be disposed on an upper surface of the testing chamber. In one or more embodiments described above or elsewhere herein, the first stage is moveable horizontally along a X axis, the second stage is moveable horizontally along a Y axis, and the third stage is moveable vertically along a Z axis.

[0009] A method for testing a substrate within an integrated test assembly is also provided. In one or more embodiments, a substrate to be tested is loaded into the testing chamber above having one or more testing devices disposed on an upper surface of the testing chamber. Once the substrate to be tested is loaded in the testing chamber, the third stage elevates to position the substrate in a testing position. The first and second stages move in an X or Y dimension to position the substrate beneath the one or more testing devices. After testing is complete, the third stage is lowered to transfer the tested substrate on an upper surface of the end effector disposed on the second stage. The end effector having the tested substrate disposed thereon then extends into a load lock chamber disposed adjacent a first side of the testing chamber, and transfers the tested substrate to the load lock chamber. The end effector then retracts to the testing chamber.

BRIEF DESCRIPTION OF THE DRAWINGS

[0010] So that the manner in which the above recited features of the present invention can be understood in detail, a more particular description of the invention, briefly summarized above, may be had by reference to embodiments, some of which

are illustrated in the appended drawings. It is to be noted, however, that the appended drawings illustrate only typical embodiments of this invention and are therefore not to be considered limiting of its scope, for the invention may admit to other equally effective embodiments.

[0011] Figure 1 is a schematic view of one embodiment of an integrated electron beam test assembly as described herein.

[0012] Figure 2 is a schematic plan view of one embodiment of a prober transfer assembly.

[0013] Figure 3 is an enlarged schematic view of one embodiment of a load lock chamber.

[0014] Figure 4 is a partial cross section view of the load lock chamber and the testing chamber.

[0015] Figure 5 is an enlarged cross section view of the embodiment of the testing chamber shown in Figure 4.

[0016] Figures 6A and 6B are enlarged schematic views of the drive systems according to one embodiment described herein.

[0017] Figure 7 is a schematic plan view of one embodiment of an end effector shown in an extended position from the substrate table.

[0018] Figure 8 is an enlarged partial cross section view of the testing chamber shown in Figure 5.

[0019] Figure 9 is another enlarged cross section view of the testing chamber of Figure 5.

[0020] Figure 10 is a basic schematic plan view of the embodiment of the transfer module as it is shown in cross section in Figure 9.

[0021] Figure 10A shows an exemplary testing pattern showing twelve different test locations.

[0022] Figures 11-20 are partial cross section views of the embodiment of the load lock chamber and the testing chamber illustrating the sequence of operation of a transfer module disposed within the testing chamber.

DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT

[0023] **Figure 1** shows a schematic view of an electron beam test system 100. The electron beam test system 100 is an integrated system requiring minimum space, and is capable of testing large glass panel substrates, up to and exceeding 1.9 meters by 2.2 meters. As will be described below, the electron beam test system 100 provides stable substrate handling, reduces both substrate and prober alignment time, reduces unwanted particle generation, and provides improved test accuracy, reliability and repeatability.

[0024] Referring to Figure 1, the electron beam test system 100 includes a prober storage assembly 200, a prober transfer assembly 300, a load lock chamber 400, and a testing chamber 500. The prober storage assembly 200 houses one or more probers 205 proximal the test chamber 500 for easy use and retrieval. Preferably, the prober storage assembly 200 is disposed beneath the test chamber 500 as shown in Figure 1, reducing the clean room space needed for a contaminant free and efficient operation. The prober storage assembly 200 preferably has dimensions approximating those of the testing chamber 500 and is disposed on a mainframe 210 supporting the testing chamber 500. The prober storage assembly 200 includes a shelf 220 disposed about the mainframe 210 to provide a support for the one of more probers 205. The prober storage assembly 200 may further include a retractable door 230 that can seal off the storage area and protect the stored probers 205 when not in use.

[0025] **Figure 2** shows a schematic plan view of the prober transfer assembly 300. The prober transfer assembly 300 is a modular unit disposable near the testing

chamber 500 for transferring a prober 205 between the prober storage assembly 200 and the test chamber 500. The prober transfer assembly 300 includes a base 305 connected to two or more vertical support members 310A, 310B (two are shown). Wheels or casters 315 may be arranged on a bottom surface of the base 305 to easily maneuver the assembly 300 when desired.

[0026] The prober transfer assembly 300 further includes a lift arm 320 that is attached at one end thereof to the support members 310A, 310B. The support members 310A, 310B each include a recessed track 312 (one is shown in this view) for mating engagement with the lift arm 320. The recessed tracks 312, one or both, may house a linear actuator, a pneumatic cylinder, a hydraulic cylinder, a magnetic drive, a stepper or servo motor, or other type of motion device (not shown). The recessed tracks 312 working in conjunction with the motion device (not shown) guide and facilitate the vertical movement of the lift arm 320. A second motion device (not shown) or pair of motion devices (also not shown) may be coupled to the lift arm 320 to move the lift arm 320 in a horizontal direction. This horizontal movement facilitates the insertion of the lift arm 320 having the prober 205 disposed thereon within the testing chamber 500 or within the storage assembly 200 to deliver the prober 205, as explained in more detail below. Likewise, the horizontal movement of the lift 320 facilitates the retrieval of a prober 205 from the testing chamber 500 or from the storage assembly 200. These above mentioned horizontally and vertically actuated motors may be combined into a single motor capable of moving the lift arm 320 in both directions. Such a combined motor may be located in one or both of the recessed tracks 312 or coupled to the lift arm 312.

[0027] In operation, the lift arm 320 supports the prober 205 on an upper surface thereof, and is raised or lowered by the linear motors (not shown) disposed within the recessed tracks 312 to align the prober 205 at the elevation of the testing chamber 500 or the storage assembly 200. The lift arm 320 is then extended or retracted by the horizontal linear motor to transfer the prober 205 in or out of the testing chamber 500 or storage assembly 200.

[0028] Referring again to **Figure 1**, the load lock chamber 400 is disposed adjacent and connected to the testing chamber 500. These chambers 400, 500 share a common environment which is typically maintained at vacuum conditions by a pump (not shown) coupled through the testing chamber 500. The load lock chamber 400 transfers substrates between the transfer chamber 500 and the outside which is typically a clean room at atmospheric pressure. The load lock chamber 400 may function as an isolated processing environment that is capable of being heated or cooled as well as pressurized or de-pressurized, depending on system requirements. Consequently, load lock chamber 400 enables the transfer of substrates into and out of the testing chamber 500 without exposure to outside contaminants.

[0029] **Figure 3** shows an enlarged schematic view of one embodiment of a load lock chamber 400 having a dual slot substrate support. The load lock chamber 400 includes a chamber body 402 and a dual slot substrate support 422 disposed therein. The chamber body 402 includes at least a first sealable port 404 and a second sealable port 406 formed through sidewalls 408, 410 thereof as shown. Each port 404, 406 is selectively sealable by a slit valve (not shown) to isolate an interior environment of the chamber body 402. The first port 404 typically couples the load lock chamber 400 to a factory interface (substrate queuing system), a processing system or other device (not shown). The second port 406 is typically disposed between the load lock chamber 400 and the testing chamber 500 to facilitate substrate transfer therebetween.

[0030] A pumping system (not shown), coupled to the load lock chamber 400 through a pumping port (also not shown for simplicity purposes), allows pressure within the load lock chamber 400 to be decreased or increased to a level substantially equal to that of the pressure within the testing chamber 500. A vent (not shown), having a flow control valve (not shown) in communication therewith, is formed through the chamber body 402 of the load lock chamber 400. The control valve may be selectively opened to deliver filtered gas into the load lock chamber 400, thereby raising or lowering the pressure within the load lock chamber 400 to a

level substantially equal to the pressure in the device (not shown) coupled to the load lock chamber 400 through the first port 406.

[0031] The dual slot support 422 is disposed on a shaft (not shown) connected to a lift mechanism (also not shown). The lift mechanism allows the dual slot support 422 to move vertically within the chamber body 402 to facilitate substrate transfer to and from the load lock chamber 400. The dual slot support 422 includes a first substrate support tray 424 and a second substrate support tray 426 that are maintained in a stacked, spaced-apart relationship by a pair of vertical supports 428.

[0032] The load lock chamber 400 may include a heater and/or cooler disposed therein to control the temperature of the substrates positioned within the load lock chamber 400. For example, one or more heating plates and one or cooling plates (not shown) may be attached to the substrate support trays 424, 426. Also for example, a heat exchanger (not shown) may be disposed within the sidewalls of the chamber body 402. Alternatively, a non-reactive gas, such as nitrogen for example, may be passed through the load lock chamber 400 to transfer heat in and out of the chamber 400.

[0033] Each tray 424, 426 is configured to support a substrate thereon (not shown). Typically, one or more support pins 429 are coupled to an upper surface of each substrate support tray 424, 426 or at least partially disposed therethrough to support a substrate. The support pins 429 may be of any height, and provide a pre-determined spacing or gap between a lower surface of the substrate and the upper surface of the substrate support tray 424 or 426. The gap prevents direct contact between the substrate support trays 424, 426 and the substrates, which might damage the substrates or result in contaminants being transferred from the substrate support trays 424, 426 to the substrates.

[0034] In one aspect, the support pins 429 have a rounded upper portion that contacts a substrate disposed thereon. The rounded surface reduces surface area in contact with the substrate thereby reducing the chances of breaking or chipping the substrate disposed thereon. In one embodiment, the rounded surface

resembles a hemispherical, ellipsoidal, or parabolic shape. The rounded surface may have either a machined or polished finish or other suitable finish of adequate smoothness. In a preferred embodiment, the rounded surface has a surface roughness no greater than 4 micro inches. In another aspect, the rounded upper portion of the support pin 429 is coated with a chemically inert material to reduce or eliminate chemical reactions between the support pin 429 and the substrate supported thereon. Additionally, the coating material may minimize friction with the substrate to reduce breakage or chipping. Suitable coatings include nitride materials, such as silicon nitride, titanium nitride, and tantalum nitride, for example. A more detailed description of such support pins and coatings may be found in U.S. Patent No. 6,528,767.

[0035] In another aspect, the support pins 429 may be a two piece system comprising a mounting pin disposed on an upper surface of the support tray 422, 426, and a cap disposable on the mounting pin. The mounting pin is preferably made of a ceramic material. The cap includes a hollow body to receive the mounting pin. The upper portion of the cap may be rounded and smoothed as discussed above. Similarly, the cap may be coated as described above. A more detailed description of such a two piece system may also be found in U.S. Patent No. 6,528,767.

[0036] In yet another aspect, an upper portion of the support pins 429 may include a socket that retains a ball moveable within the socket. The ball makes contact with and supports the substrate disposed thereon. The ball is allowed to rotate and spin, much like a ball bearing, within the socket allowing the substrate to move across the ball without scratching. The ball is generally constructed of either metallic or non-metallic materials that provide friction reduction and/or inhibit chemical reaction between the ball and the substrate. For example, the ball may include a metal or metal alloy, quartz, sapphire, silicon nitride or other suitable non-metallic materials. Preferably, the ball has a surface finish of 4 micro-inches or smoother. The ball may further include the coating describe above. A more detailed description of such a support pin may be found in U.S. Patent No. 6,528,767.

[0037] Alternatively, the support pins 429 may be a two piece system comprising a mounting pin disposed on an upper surface of the support tray 422 or 426, and a cap disposable on the mounting pin, whereby the cap includes the socket and ball configuration described above. A more detailed description of such a ball and socket may be found in co-pending U.S. Patent Application, serial no. 09/982,406, as well as serial no 10/376,857, both entitled "Substrate Support", and both assigned to Applied Materials, Inc.

[0038] Further, the support pins 429 may include a housing having one or more roller assemblies and a support shaft at least partially disposed therein. The support shaft is able to move axially through the housing as well as rotate within the housing to reduce wear and tear on the pin head during loading and unloading of a substrate supported thereon. The support pins 429 may also include a housing having one or more ball assemblies and a support shaft at least partially disposed therein. The ball assemblies include one or more spherical members that are held into place by a sleeve that is at least partially disposed about the housing. The one or more spherical members contact the shaft and allow the shaft to move axially as well as radially within the housing. This also reduces wear and tear on the pin head during loading and unloading of a substrate supported thereon. A more detailed description of such support pins may be found in commonly assigned and co-pending U.S. Patent Application, serial no. 10/779,130 entitled "Support Bushing for Flat Panel Substrates."

[0039] **Figure 4** shows a partial cross section view of the load lock chamber 400 and the testing chamber 500. The testing chamber 500 includes a housing 505, one or more electron beam testing (EBT) columns 525A/B (two are shown in this view), a base 535, and a substrate table 550. Four EBT columns 525 A, B, C, D are shown in Figure 1. The EBT columns 525A/B/C/D are disposed on an upper surface of the housing 505 and are coupled to the housing 505 via a port 526A/B formed through the upper surface thereof. The housing 505 provides a particle free environment and encloses the substrate table 550 and the base 535. The base 535 is fixed at the bottom of the housing 505 and supports the substrate table 550.

[0040] Considering the substrate table 550 in more detail, **Figure 5** shows an enlarged cross section view of the testing chamber 500 shown in Figure 4. The substrate table 550 includes a first stage 555, a second stage 560, and third stage 565. The three stages 555, 560, and 565 are planar monoliths or substantially planar monoliths, and are stacked on one another. In one aspect, each of the three stages 555, 560, 565 independently move along orthogonal axes or dimensions. For simplicity and ease of description, the first stage 555 will be further described below as representing the stage that moves along the X-axis and will be referred to as the lower stage 555. The second stage 560 will be further described below as representing the stage that moves along the Y-axis and will be referred to as the upper stage 560. The third stage 565 will be further described below as representing the stage that moves along the Z-axis and will be referred to as the Z-stage 565.

[0041] The lower stage 555 and the upper stage 560 each may move side to side or forward and backward, depending on the orientation of the testing chamber 500. In other words, the lower stage 555 and the upper stage 560 both move linearly on the same horizontal plane, but move in a direction orthogonal to one another. In contrast, the Z-stage 565 moves in a vertical direction or the "Z direction." For example, the lower stage 555 moves side to side in the "X direction", the upper stage 560 moves forward and backward in the "Y direction" and the Z-stage 565 moves up and down in the "Z direction."

[0042] The lower stage 555 is coupled to the base 535 through a first drive system (not shown in this view). The first drive system moves the lower stage 555 linearly along the X axis. Similarly, the upper stage 560 is coupled to the lower stage 555 through a second drive system, (not shown in this view) which moves the upper stage 560 linearly along the Y axis. The first drive system is capable of moving the substrate table 550 in the X direction or dimension by at least 50 percent of the width of the substrate. Likewise, the second drive system is capable of moving the substrate table 550 in the Y direction or dimension by at least 50 percent of the length of the substrate.

[0043] **Figures 6A and 6B** show an enlarged schematic view of these drive systems. Referring to Figure 6A, the first drive system 722 generally includes a pair of linear rails 702A coupled to the base 535. A plurality of guides 706A are movably engaged with the rails 702A and are coupled to a first side 704A of the lower stage 555 (not shown in this view). The guides 706A move along the rails 702A, thereby allowing the lower stage 555 to move over the base 535 in a first direction, i.e., along the X-axis. Linear motor 708A, such as a ball screw and motor, is coupled between the lower stage 555 and the base 535 to control the position of the guides 706A. The lower stage 555 is coupled to each of the guides 706A, allowing the lower stage 555 to move in response to the actuator 708A. In addition to linear actuators, other types of motion devices may be used as well, such as a pneumatic cylinder, a hydraulic cylinder, a magnetic drive, or a stepper or servo motor, for example.

[0044] Referring to Figure 6B, the upper stage 560 is coupled to the lower stage 555 via the second drive system 726. The second drive system 726 is configured similar to the first drive system 722 except the second drive system 726 is oriented in a direction orthogonal to the first drive system 722. Similar to the lower stage 555 above, a lower surface of the upper stage 560 is coupled to each of the guides 706B, allowing the upper stage 560 to move in response to the linear motor 708B. Generally, the drive systems 722, 726 have a range of motion that allows all of the surface area of a substrate disposed within the testing chamber 500 to be moved beneath the EBT columns 525 during testing.

[0045] Referring back to Figure 5, the testing chamber 500 further includes an end effector 570 to transfer a substrate 585 in and out of the testing chamber 500. In operation, the end effector 570 may be extended from the testing chamber 500 into the load lock chamber 400 to load a substrate. Likewise, the end effector 570 having a substrate loaded thereon may be extended from the testing chamber 500 into the load lock chamber 400 to transfer the substrate to the load lock chamber 400. A motion device, such as a linear actuator, a pneumatic cylinder, a hydraulic cylinder, a magnetic drive, or a stepper or servo motor, for example may be coupled

to the end effector 570 to assist this transfer. In one aspect, the end effector 570 includes a pair of bearing blocks 572 that permit the end effector 570 to move in and out of the testing chamber 500.

[0046] The end effector 570 has a planar or substantially planar upper surface on which the substrate 585 may be supported. In one embodiment, the end effector 570 is a slotted monolith that rests on an upper surface of the upper stage 560. Figure 5 shows one embodiment of the end effector 570 having four fingers that are evenly spaced, which contact and support the substrate 585 when placed thereon. The actual number of fingers is a matter of design and is well within the skill of one in the art to determine the appropriate number of fingers needed for the size of substrate to be manipulated.

[0047] The Z-stage 565 is disposed on an upper surface of the upper stage 560. The Z-stage 565 has a planar or substantially planar upper surface to contact and support the substrate 585 within the testing chamber 500. The Z-stage 565 is slotted or segmented such that each segment of the Z-stage 565 sits adjacent the fingers of the end effector 570. As such the Z-stage 565 and the end effector 570 can be interdigitated on the same horizontal plane. This configuration allows the Z-stage 565 to move above and below the end effector 570. Accordingly, the spacing between the segments of the Z-stage 565 corresponds to the width of the fingers of the end effector 570 plus some additional measure to assure clearance. Although five segments are shown in the cross section view of Figure 5, the Z-stage may have any number of segments.

[0048] Still referring to Figure 5, one or more Z-stage lifts 575 is coupled to the back side of each of the segments making up the Z-stage 565. Each Z-stage lift 575 is disposed within a channel 576 formed in the upper stage 560, and a bellows 577 is arranged about each Z-stage lift 575 to reduce particle contamination within the testing chamber 500. The Z-stage lift 575 moves up and down vertically and may be actuated pneumatically or electrically. The bellows 577 compress and expand in response to the movement of the lift 575.

[0049] **Figure 7** shows a schematic plan view of the end effector 570 shown in an extended position from the substrate table 550. The end effector 570 extends from the testing chamber 500 (not shown) to the load lock chamber 400 (not shown) to transfer substrates therebetween. The sequence of which is described in more detail below. As shown in Figure 7, the end effector includes four fingers 571A-D that have extended away from the five segments 566A-E of the Z-stage 565. The substrate 585 is disposed on and supported by the fingers 571A-D. The fingers 571A-D move in and out of the Z-stage 565 such that the fingers 571A-D interdigitate with the segments 566A-E when the end effector 570 is disposed in substantially the same plane as the Z-stage 565. This configuration allows the end effector 570 to freely extend and retract. As will be described below, the Z-stage 565 is capable of elevating above the end effector 570 to load and un-load the substrate 585 between the end effector 570 and the Z-stage 565.

[0050] **Figure 8** shows an enlarged partial cross section view of the testing chamber 500 shown in Figure 5. The Z-stage lift 575 is activated to move the Z-stage 565 vertically up and down. As shown, the Z-stage 565 is in a lowered or "substrate transfer" position. In this position, the substrate 585 rests on the upper surfaces of the fingers of the end effector 570, and does not contact the lower surface of the prober 205. Also, the lift 575 is located at the bottom of the channel 576 and the bellows 577 are extended.

[0051] Still referring to Figure 8, as shown, the prober 205 rests on a collar 579 disposed on an upper surface of the upper stage 560 and is secured to the collar 579 using a pin assembly 580. The pin assembly 580 may include a spring loaded pin 581 disposed within a recess 582 formed in the collar 579. The pin 581 extends into a matching receptacle 583 machined into the perimeter of the prober 205, securing the prober 205 to the upper stage 560.

[0052] **Figure 9** shows another enlarged cross section view of the testing chamber 500. In this view, the Z-stage 565 is shown in a raised or "substrate testing" position. In the testing position, the Z-stage lift 575 is activated, moving the

Z-stage 565 vertically upward in the "Z direction." The Z-stage 565 travels upward, traversing the fingers of the end effector 570 and lifting the substrate 585 off the end effector 570. The Z-stage 565 continues to move upward until the substrate 585 sits against the backside of the prober 205 to make an electrical connection between the prober 205 and the substrate 585. This allows the prober 205 to directly contact the substrate 585 and facilitate the electron beam test methods as described below. As shown in Figure 9, the Z-stage lifts 575 have moved to an upward portion of the channel 576, and the bellows 577 are compressed.

[0053] For further understanding, **Figure 10** shows a basic schematic plan view of the substrate table 550 as it is shown in cross section in Figure 9. The housing 505 has been removed to more easily visualize the components of the substrate table 550 in relation to the EBT testing columns 525A-D. The substrate table 550 is shown such that side 550A would be adjacent the prober transfer assembly 300 disposed toward the X direction and the side 550B would be adjacent the load lock chamber 400 disposed toward the Y direction.

[0054] As shown in this perspective, the lower stage 555 is disposed on the base 535 and moves along rails 702A. The upper stage 560 is disposed on the lower stage 555 and moves along rails 702B. The Z-stage 565 is disposed on the upper stage 560 and the end effector 570 (not shown) is disposed therebetween. The substrate 585 is resting on the upper surface of the Z-stage 565 and abuts the lower surface of the prober 205.

[0055] In operation, the substrate table 550 positions the substrate 585 and the prober 205 so that the columns 525A-D may interact with discrete portions of the substrate 585. Each column 525A-D is an electron beam generator that detects voltage levels of the devices formed on the substrate 585.

[0056] The prober 205 generally has a picture frame configuration, having sides at least partially defining at least one window or display 206 through which the columns 525A-D interact with the substrate 585. Each window 206 is positioned to allow a predefined field of pixels (or other device) formed on the substrate 585 to be

exposed to the electron beam generated by the columns 525A-D. Accordingly, the number, size and positions of the windows 206 in a particular prober 205 are chosen based upon the layout of the substrate 585 and the devices on the substrate 585 to be tested.

[0057] A face of the prober 205 contacting the substrate 585 generally includes a plurality of electrical contact pads that are coupled to a controller (not shown). The electrical contact pads are positioned to provide electrical connection between a predetermined pixel (or other device formed on the substrate 585) and the controller. Thus, as the substrate 585 is urged against the prober 205, electrical contact between the controller and the devices on the substrate 585 are made through the contact pads on the prober 205. This allows the controller to apply a voltage to a selected pixel or to monitor each pixel for changes in attributes, such as voltage, during testing.

[0058] In one embodiment, the substrate is tested by sequentially impinging at least one electron beam emitted from the columns 525A-D on discrete portions or pixels composing the thin film transistor matrix. After a pixel is tested, the substrate table 550 moves the substrate 585 to another discrete position within the testing chamber 500 so that another pixel on the substrate 585 surface may be tested.

[0059] **Figure 10A** shows an exemplary testing pattern showing twelve different test locations. The discrete portions of the substrate surface under each column 525A-D represents one test location. As shown, the substrate 585 is moved along the X-axis as shown by arrow 1001 and tested in four locations under columns 525A, 525B, 525C, and 525D. The substrate 585 is then moved along the Y-axis as shown by arrow 1002 and tested in four different locations. The substrate 585 is then moved and tested as shown by arrows 1003 and 1004 until the entire surface of the substrate 585 or the desired portions of the substrate surface have been tested using the desired electron beam test method.

[0060] Electron beam testing may employ several test methods. For example, the electron beam may be utilized to sense pixel voltages in response to the voltage

applied across the pixels or the pixel through the electrical connections in the prober 205. Alternatively, a pixel or a plurality of pixels may be driven by the electron beam which provides a current to charge up the pixel(s). The pixel response to the current may be monitored by the controller (not shown) that is coupled across the pixel by the prober 205 to provide defect information. Examples of electron beam testing are described in United States Patent No. 5,369,359, issued November 29, 1994 to Schmitt; United States Patent No. 5,414,374, issued May 9, 1995 to Brunner et al.; United States Patent No. 5,258,706, issued November 2, 1993 to Brunner et al.; United States Patent No. 4,985,681, issued January 15, 1991 to Brunner et al.; and United States Patent No. 5,371,459, issued December 6, 1994 to Brunner et al. The electron beam may also be electromagnetically deflected to allow a greater number of pixels to be tested at a given substrate table 550 position.

[0061] Figures 11-20 show partial cross section views of the load lock chamber 400 and the testing chamber 500 to illustrate the sequence of operation of the substrate table 550. **Figure 11** shows the Z-stage 565 in the "testing position." As shown, the slit valve 1101 between the load lock chamber 400 and the testing chamber 500 is closed. The substrate 585A is disposed on the upper surface of the Z-stage 565. The Z-stage 565 is raised above the fingers of the end effector 570, holding the substrate 585A against the prober 205. As described above but not shown in these cross sections, the lower stage 555 and the upper stage 560 move linearly in their respective directions to place discrete portions of the substrate 585A beneath at least one of the testing columns 525A-D. Once testing is complete, the tested substrate 585A is transferred from the testing chamber 500 and an untested substrate 585B from the load lock chamber 400 is inserted into the testing chamber 500.

[0062] Figures 12 through 16 illustrate the transfer of the tested substrate 585A from the testing chamber 500 to the load lock chamber 400. To facilitate this transfer, the slit valve 1101 is opened as shown in **Figure 12**. The Z-stage 565 is lowered transferring to the substrate 585A to the end effector 570 as shown in **Figure 13**. The end effector 570 having the substrate 585A disposed thereon

extends through the slit valve 1101 above the lower tray 424 of the dual substrate support 422, as shown in **Figure 14**. The substrate support 422 is then raised to unload the substrate 585A from the end effector 570. The substrate 585A is disposed on and held by the pins 429, as shown in **Figure 15**. The end effector 570 then retracts to the testing chamber 500, completing the exchange of the tested substrate 585A to the load lock chamber 400, as shown in **Figure 16**.

[0063] Figures 17-20 illustrate the transfer sequence of an untested substrate 585B to the testing chamber 500. To initiate this transfer, the dual substrate support 422 lowers to align the substrate 585B with the slit valve 1101, as shown in **Figure 17**. The end effector 570 extends into the load lock chamber 400 as shown in **Figure 18**, and the dual substrate support 422 lowers even further to load the substrate 585B onto the end effector 570 as shown in **Figure 19**. The end effector 577 having the substrate 585B disposed thereon retracts into the test chamber 500 and the slit valve 1101 is closed, thereby completing the transfer of the untested substrate 585B from the load lock chamber 400 to the testing chamber 500, as shown in **Figure 20**.

[0064] While the foregoing is directed to embodiments of the present invention, other and further embodiments of the invention may be devised without departing from the basic scope thereof, and the scope thereof is determined by the claims that follow. Further, all patents, publications, and other documents cited in this application are fully incorporated by reference to the extent such disclosure is not inconsistent with this application and for all jurisdictions in which such incorporation is permitted.

Claims:

1. A substrate table for supporting and transferring a substrate, comprising:
a segmented stage having an upper surface for supporting a substrate; and
an end effector comprising two or more spaced apart fingers and an upper surface for supporting a substrate, wherein the end effector is at least partially disposed and moveable within the segmented stage such that the fingers of the end effector and the segmented stage interdigitate to occupy the same horizontal plane and wherein the segmented stage is adapted to raise and lower about the end effector.
2. The substrate table of claim 1, wherein the upper surfaces of the segmented stage and the end effector are adapted to support the substrate.
3. The substrate table of claim 2, wherein the segmented stage is adapted to be lowered to transfer the substrate to the upper surface of the end effector and adapted to be elevated to transfer the substrate from the end effector to the upper surface of the segmented stage.
4. The substrate table of claim 1, further comprising a first stage moveable in a first horizontal direction.
5. The substrate table of claim 4, further comprising a second stage moveable in a second horizontal direction.
6. The substrate table of claim 5, wherein the first stage carries the end effector and segmented stage in the first horizontal direction, and the second stage carries the first stage, end effector, and segmented stage in the second horizontal direction.

7. The substrate table of claim 1, wherein the end effector is extendable from the segmented stage to transfer the substrate from a first position to a second position.
8. The substrate table of claim 7, wherein the first position is a process chamber having the substrate table at least partially disposed therein and the second position is a load lock chamber or transfer chamber.
9. A substrate table for supporting and transferring a substrate, comprising:
 - a first stage moveable in a first direction;
 - a second stage moveable in a second direction;
 - a slotted third stage moveable in a third direction; and
 - an end effector disposed on an upper surface of the second stage and moveable within the slotted third stage,wherein each stage is adapted to move independently in its respective direction and the slotted third stage is adapted to raise and lower about the end effector.
10. The substrate table of claim 9, wherein the end effector comprises two or more spaced apart fingers and the third stage is slotted such that the fingers of the end effector and the slotted third stage interdigitate to occupy the same horizontal plane.
11. The substrate table of claim 9, wherein an upper surface of the third stage and the upper surface of the end effector are adapted to support the substrate.
12. The substrate table of claim 9, wherein the third stage is adapted to be lowered to load a substrate on the end effector and to be elevated to unload the substrate from the end effector.

13. The substrate table of claim 9, wherein the lower stage is adapted to move the substrate table along an X axis by at least 50 percent of the width of the substrate, and wherein the upper stage is adapted to move the substrate table along a Y axis by at least 50 percent of the length of the substrate.
14. A substrate table for supporting and transferring a substrate, comprising:
a monolith having an upper surface for supporting a substrate and two or more slots formed in the upper surface; and
an end effector comprising two or more spaced apart fingers and an upper surface for supporting a substrate, wherein the fingers are at least partially disposed and moveable within the slots of the monolith such that the fingers of the end effector and the monolith interdigitate to occupy the same horizontal plane and wherein the monolith is adapted to raise and lower about the fingers of the end effector.
15. The substrate table of claim 14, wherein the upper surfaces of the monolith and the end effector are adapted to support the substrate.
16. The substrate table of claim 15, wherein the monolith is adapted to be lowered to transfer the substrate to the upper surface of the end effector and adapted to be elevated to transfer the substrate from the end effector to the upper surface of the monolith.
17. The substrate table of claim 14, wherein the monolith has four slots formed in the upper surface thereof and the end effector has four fingers adapted to move through the four slots.
18. A prober assembly comprising:
a base;
at least two support arms each connected to the base, wherein each arm includes a recessed track to house a first motion device;

a lift arm connected to the at least two support arms at a first end thereof; and
a prober supported on the lift arm, the prober having a first side that includes
a plurality of electrical contact pads.

19. The assembly of claim 18, wherein the lift arm is moveable in a direction
perpendicular to the support arms.

20. The assembly of claim 25, wherein the lift arm is moveable in a direction
parallel to the support arms.

21. The assembly of claim 19, further comprising a second motion device
coupled to the lift arm for moving the lift arm in the horizontal direction.

22. The assembly of claim 18, wherein the base includes a plurality of wheels or
casters.

23. The assembly of claim 18, wherein the first motion device includes a linear
actuator.

24. The assembly of claim 18, wherein the base has three sides that are
enclosed by a frame member and an open fourth side.

25. The assembly of claim 18, wherein the lift arm includes four interconnected
support arms.

26. The assembly of claim 25, wherein the interconnected support arms each
include a surface for supporting the prober.

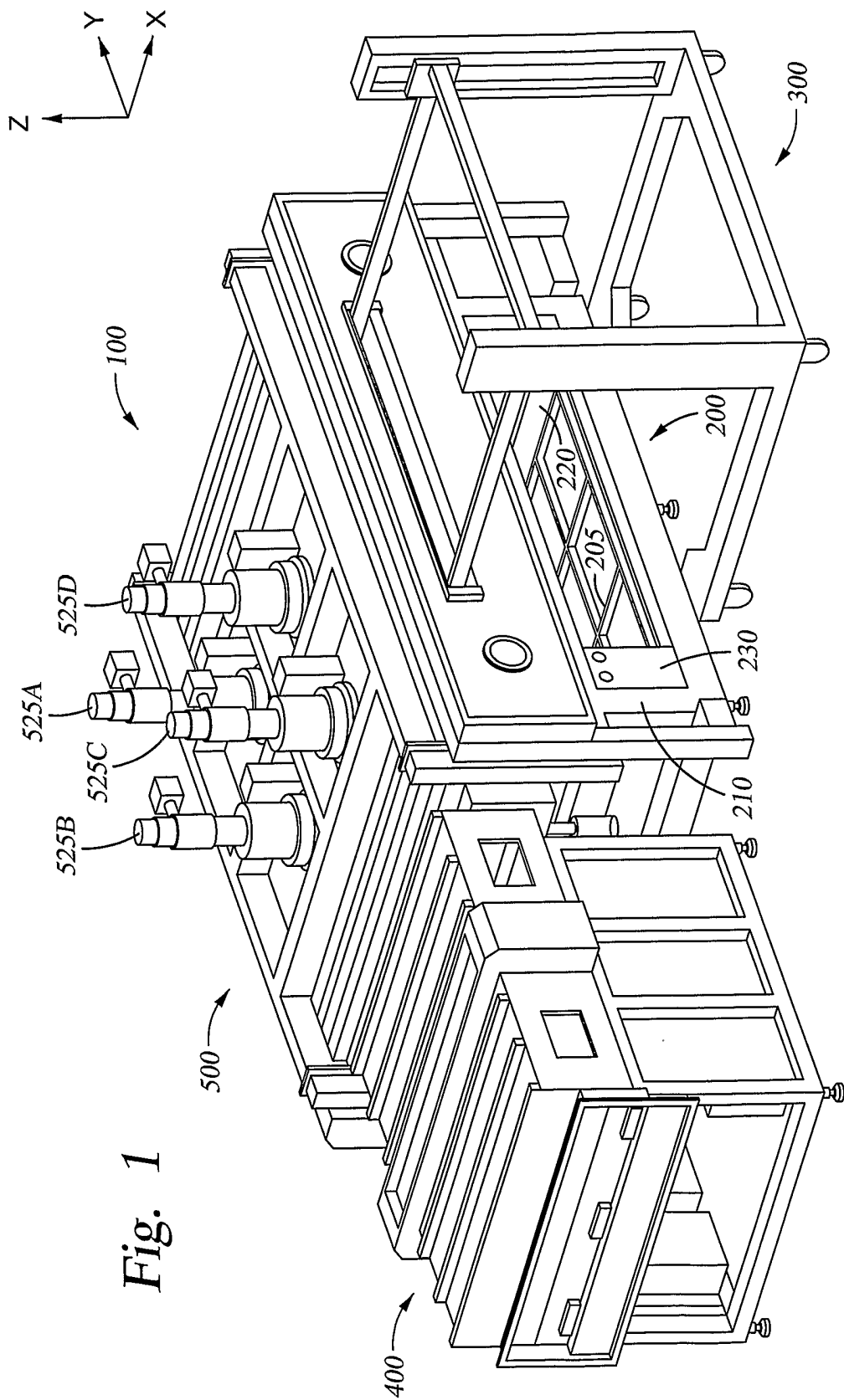


Fig. 1

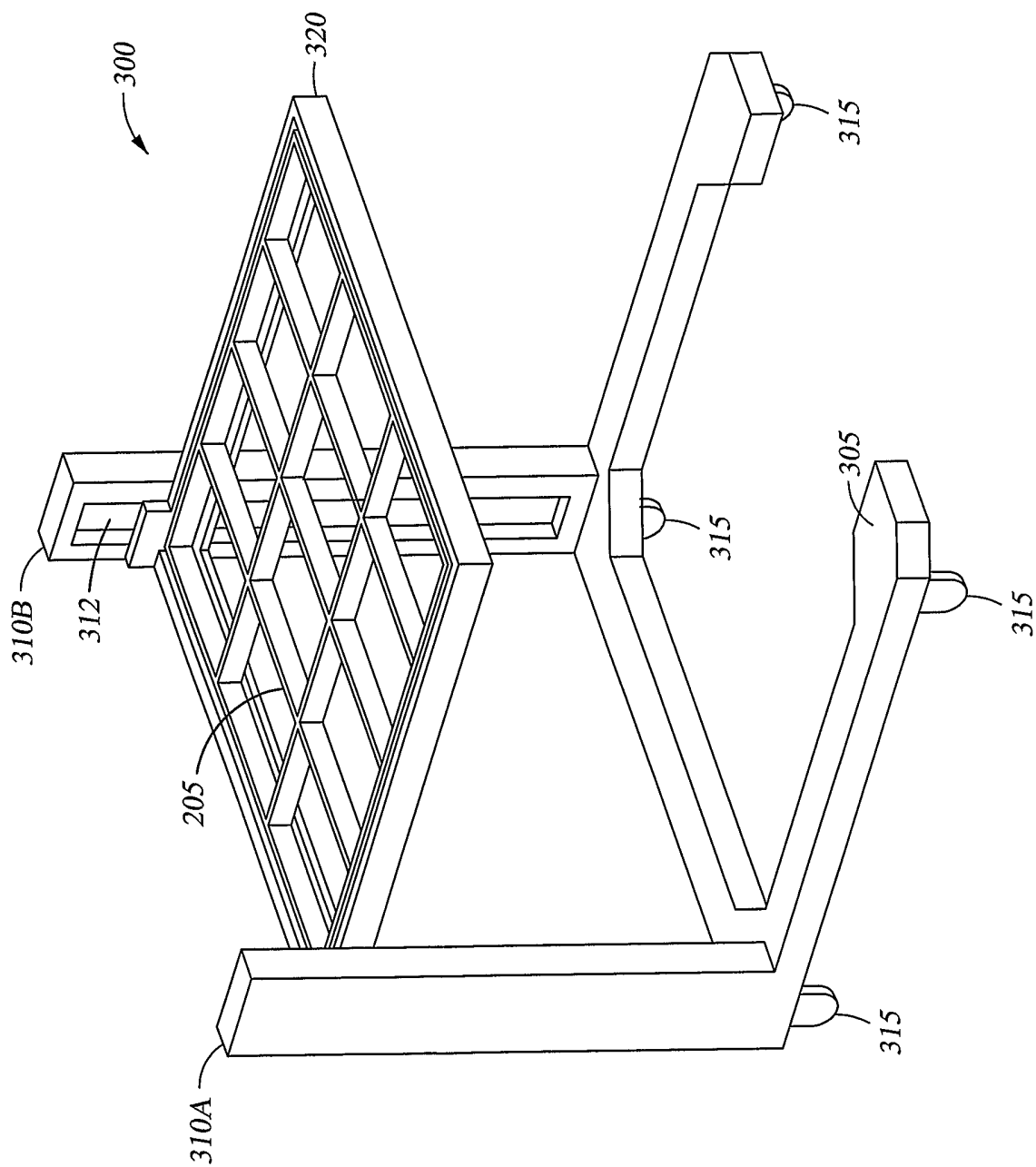


Fig. 2

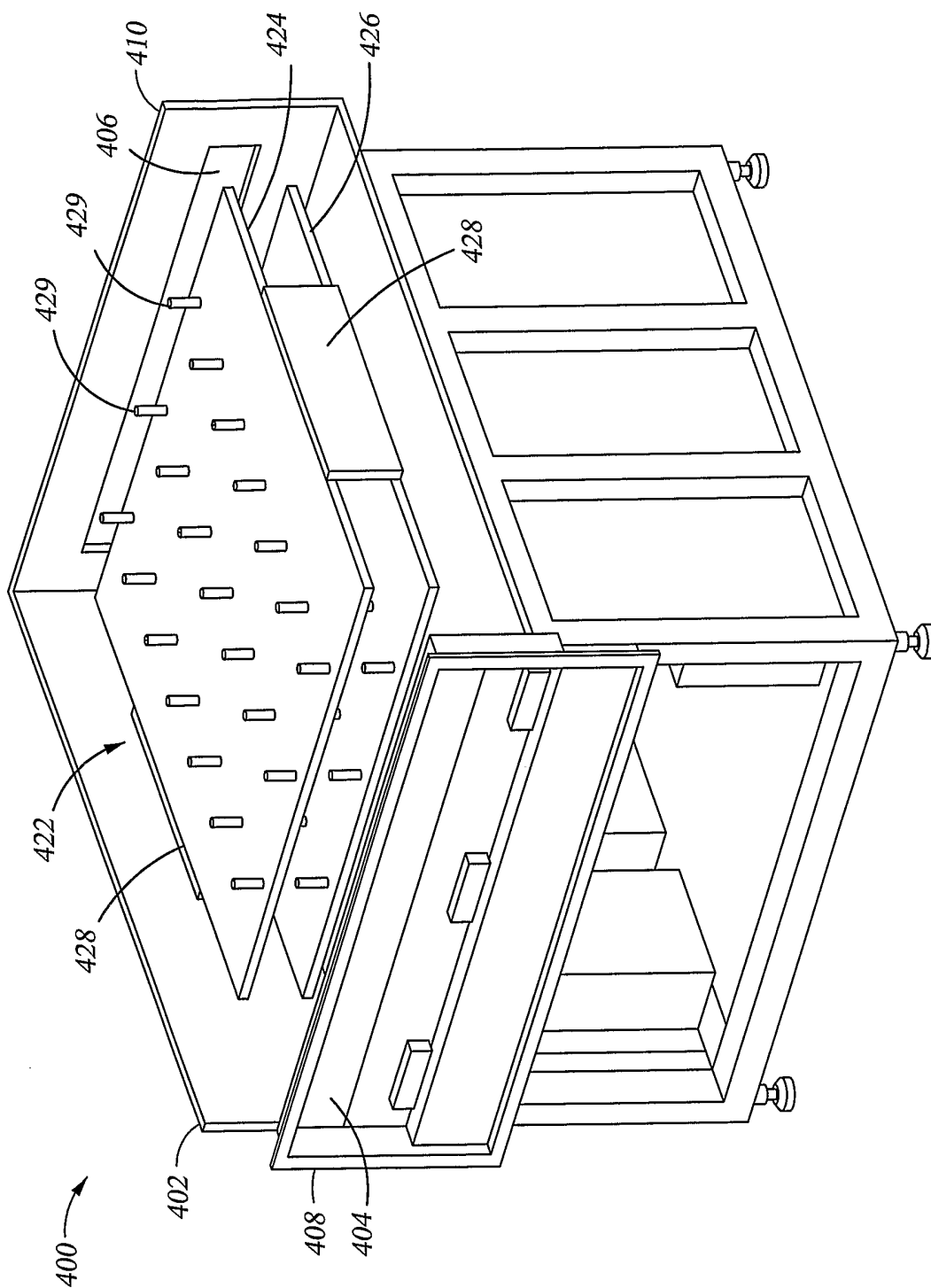


Fig. 3

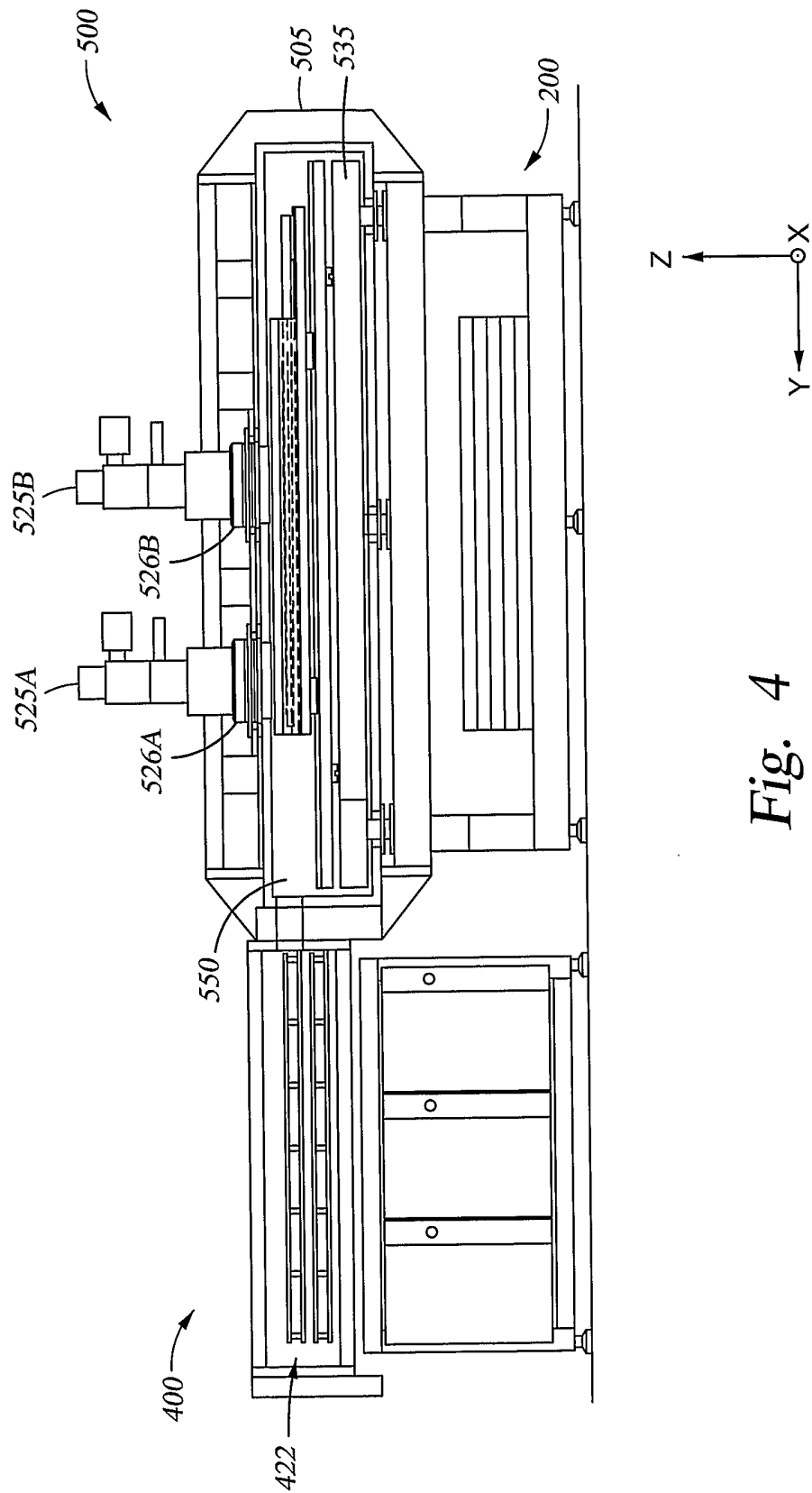


Fig. 4

5/15

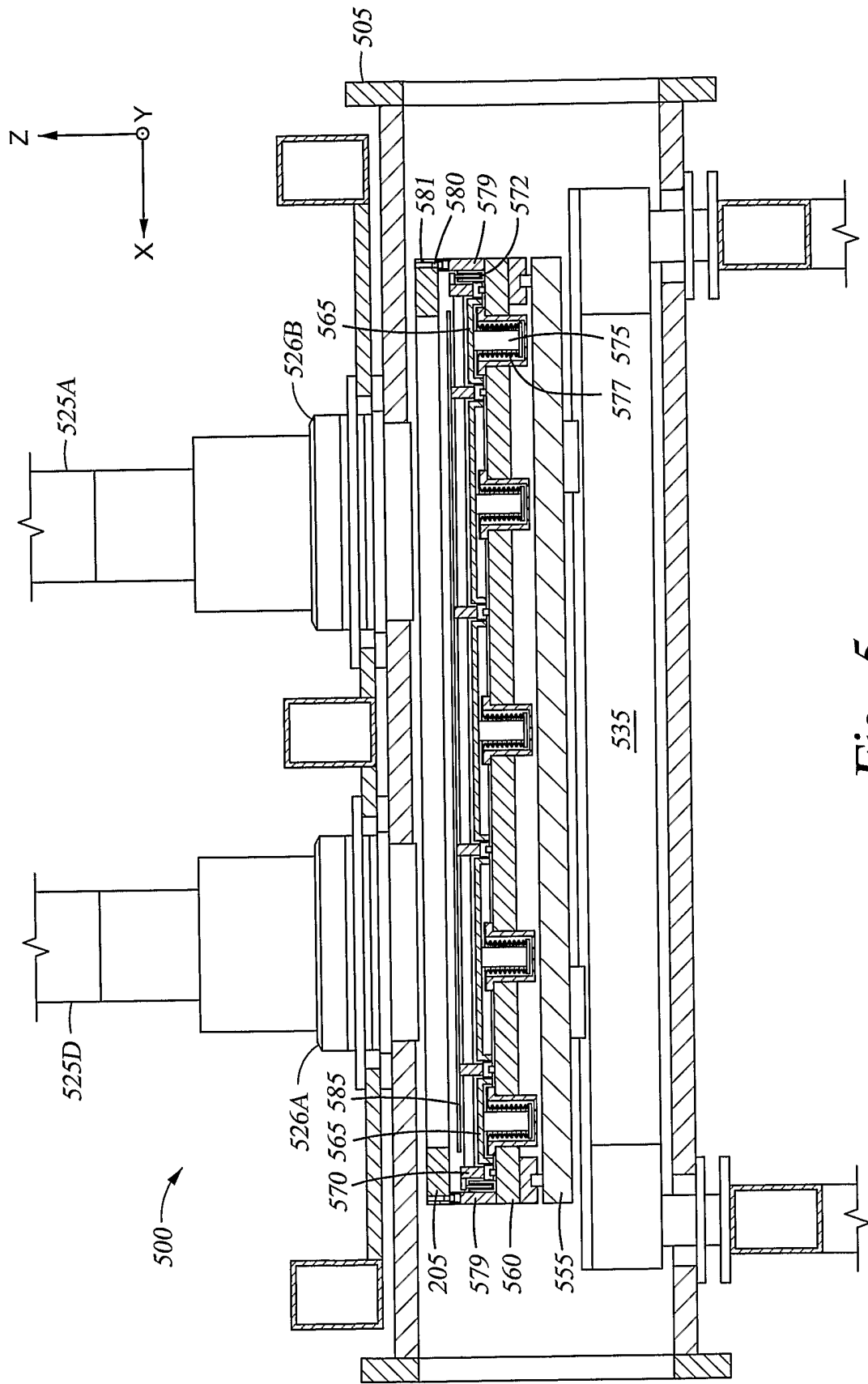


Fig. 5

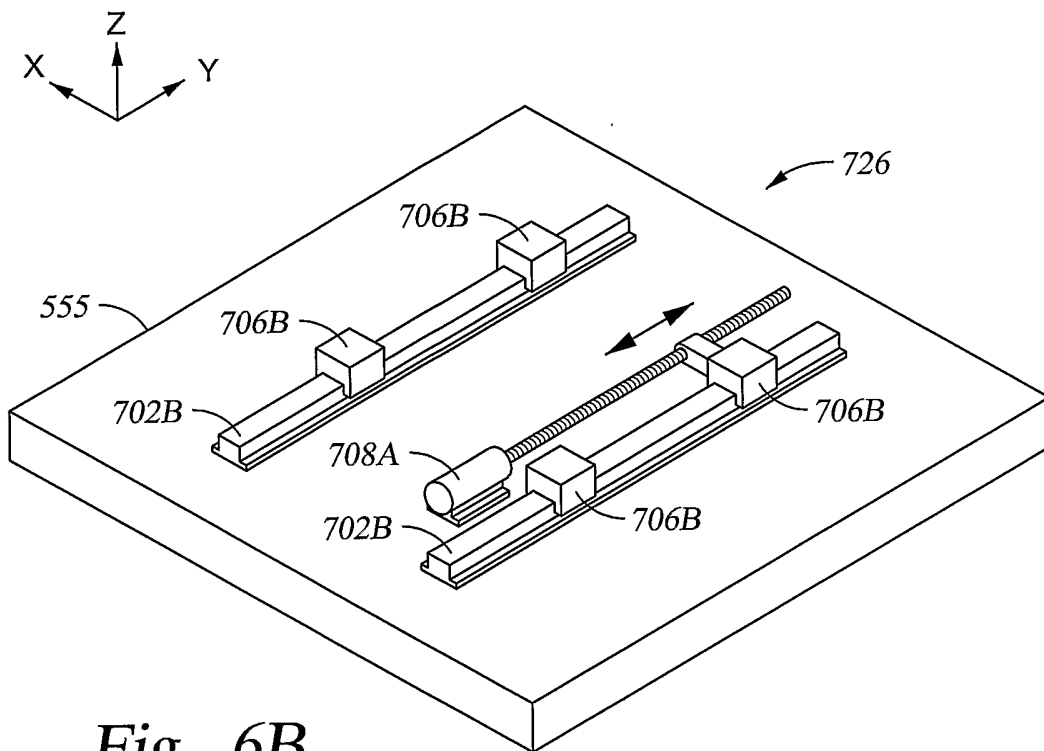


Fig. 6B

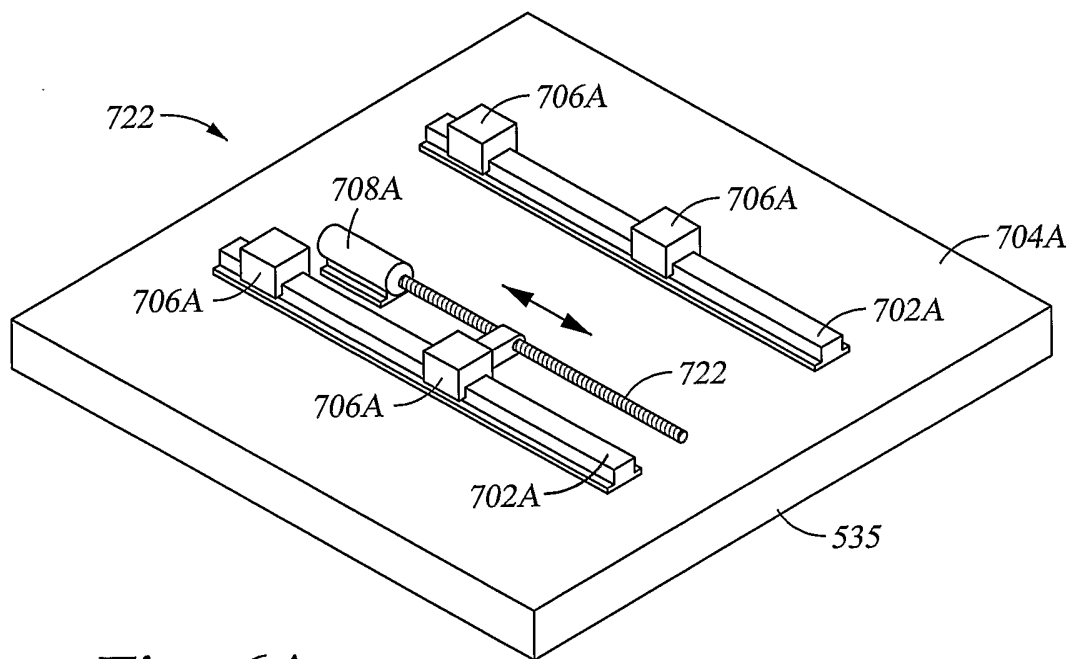


Fig. 6A

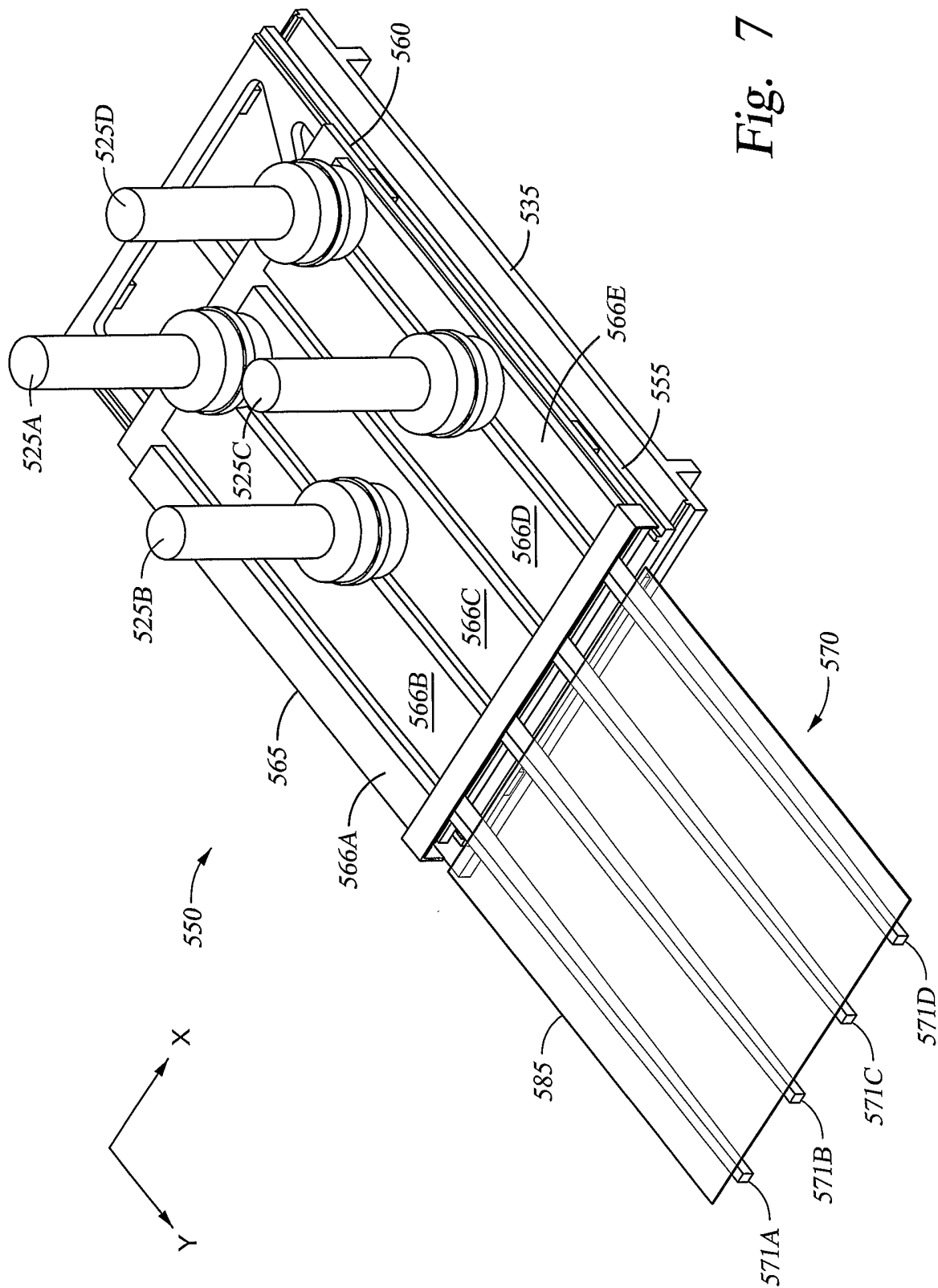


Fig. 7

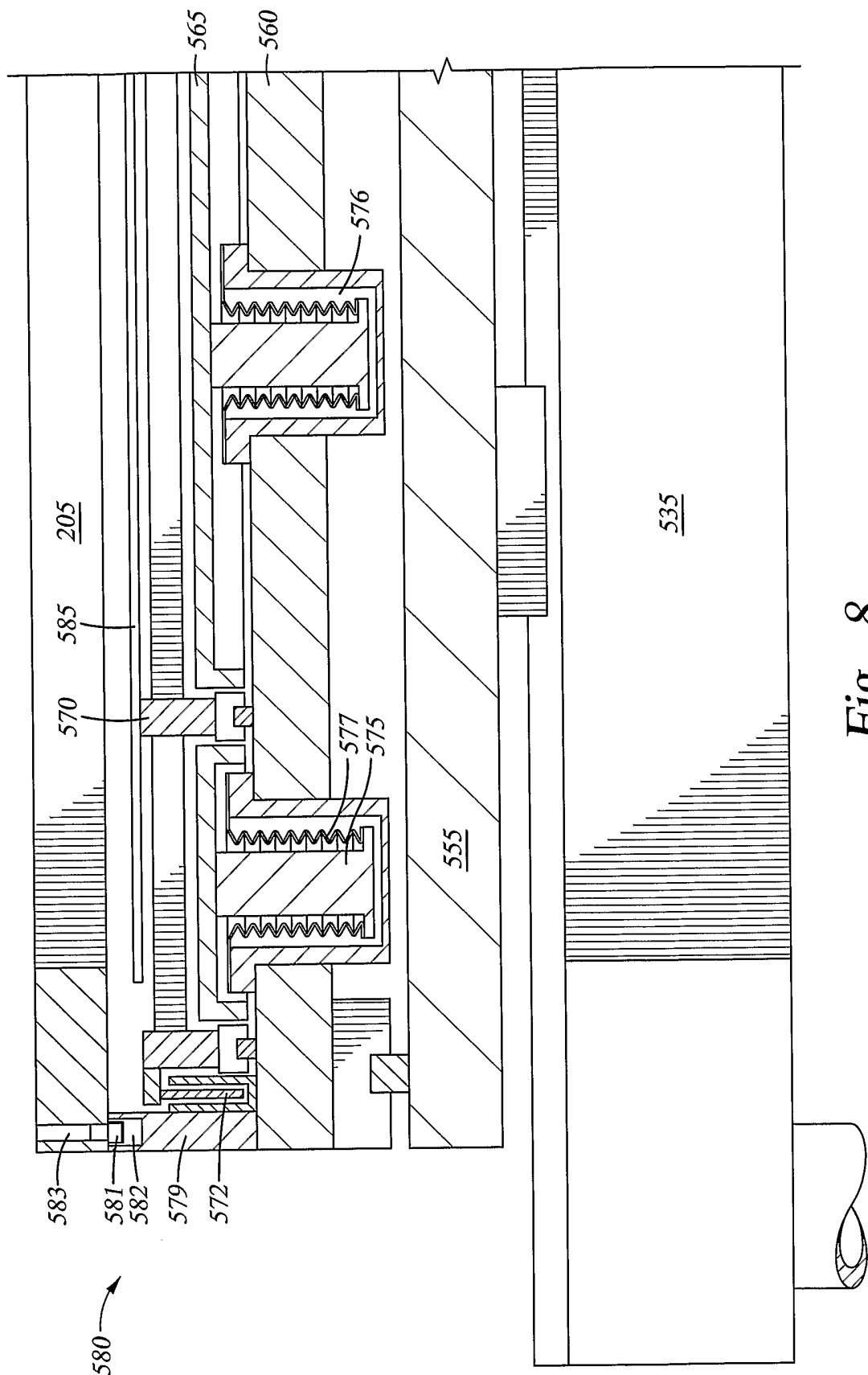


Fig. 8

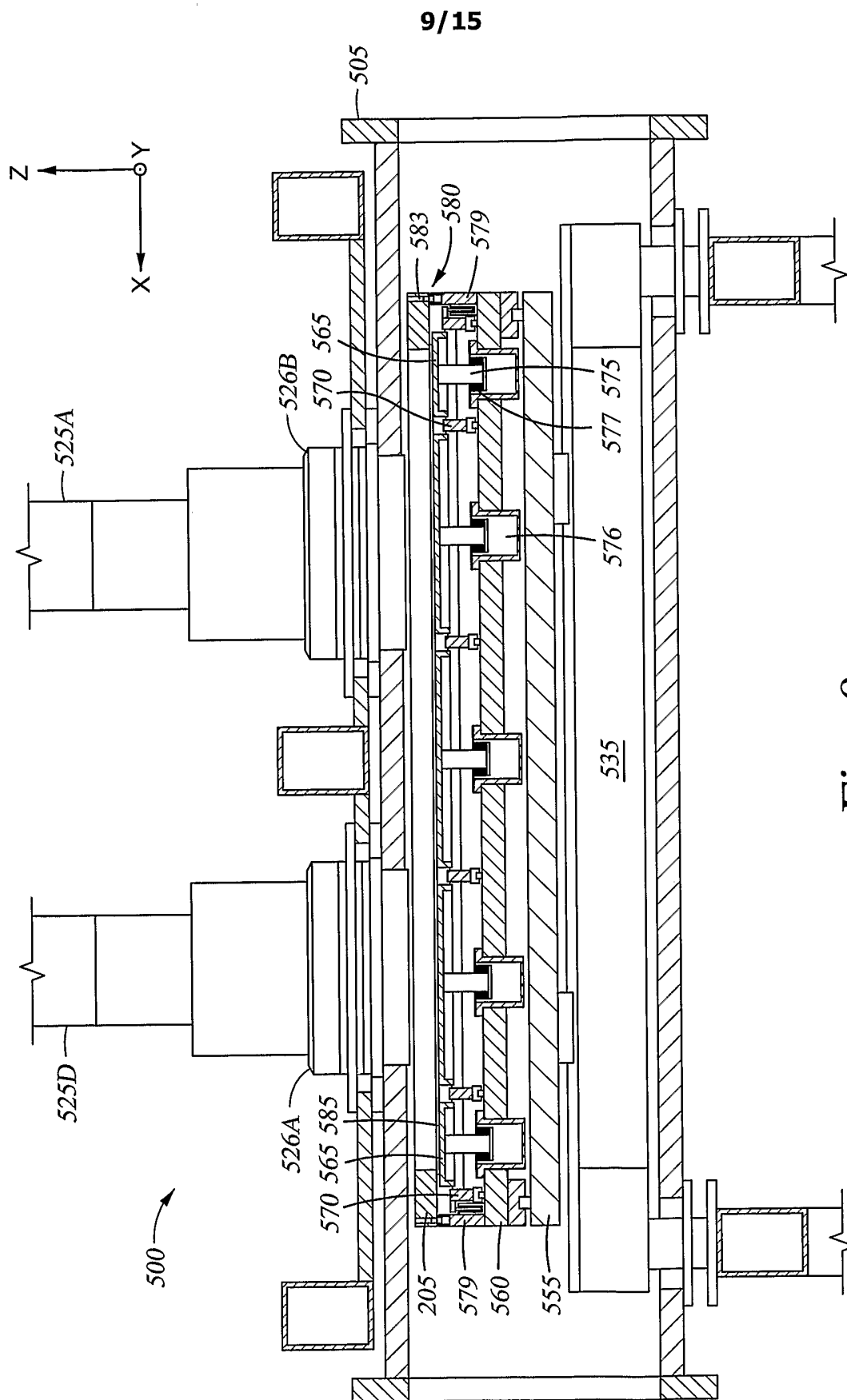


Fig. 9

10/15

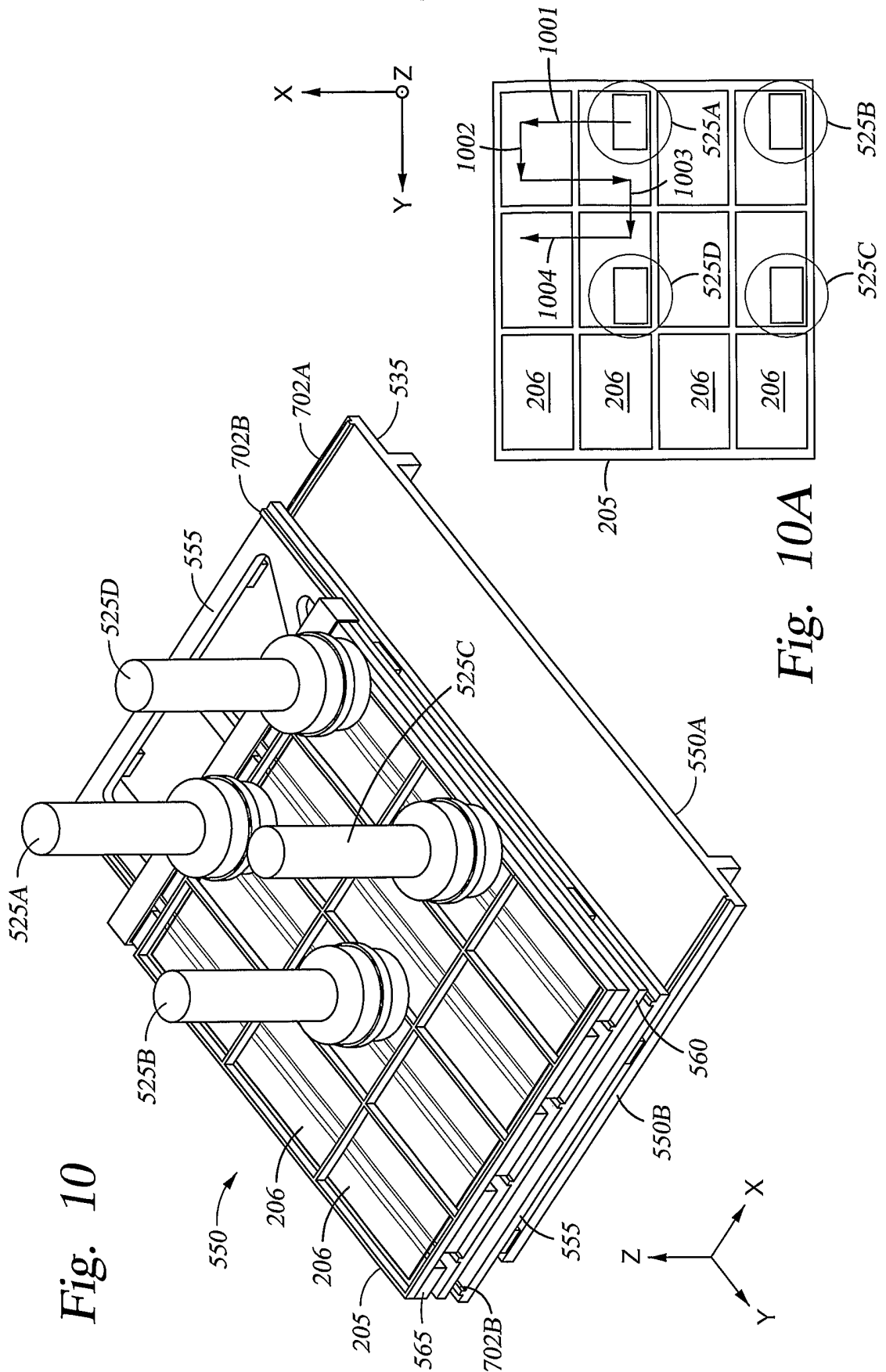


Fig. 10A

Fig. 10

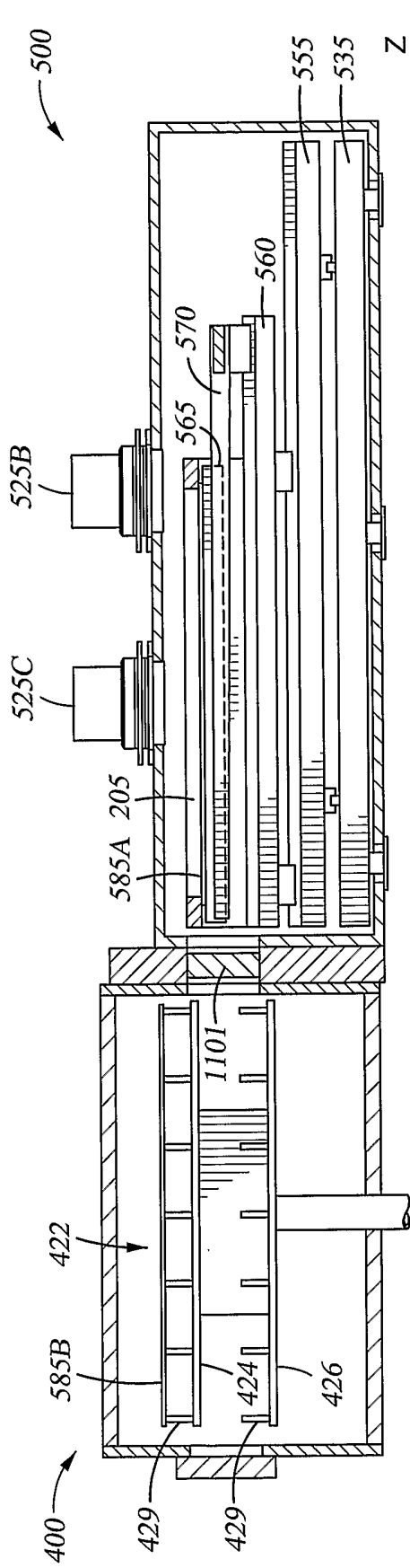


Fig. 11

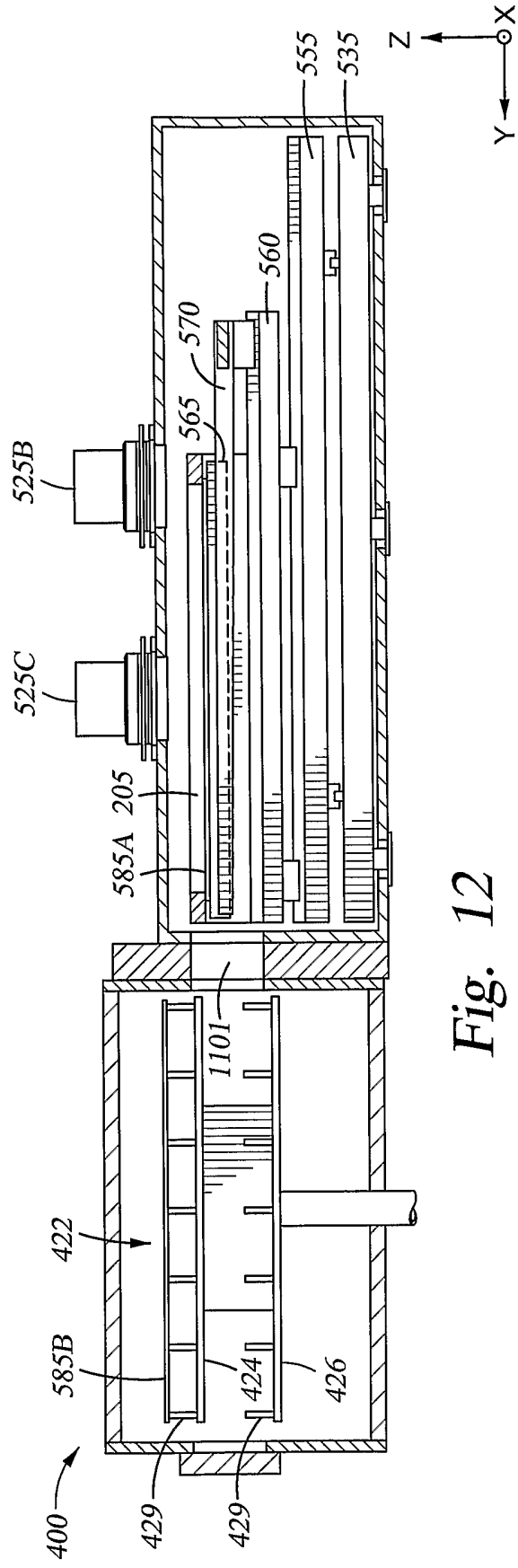


Fig. 12

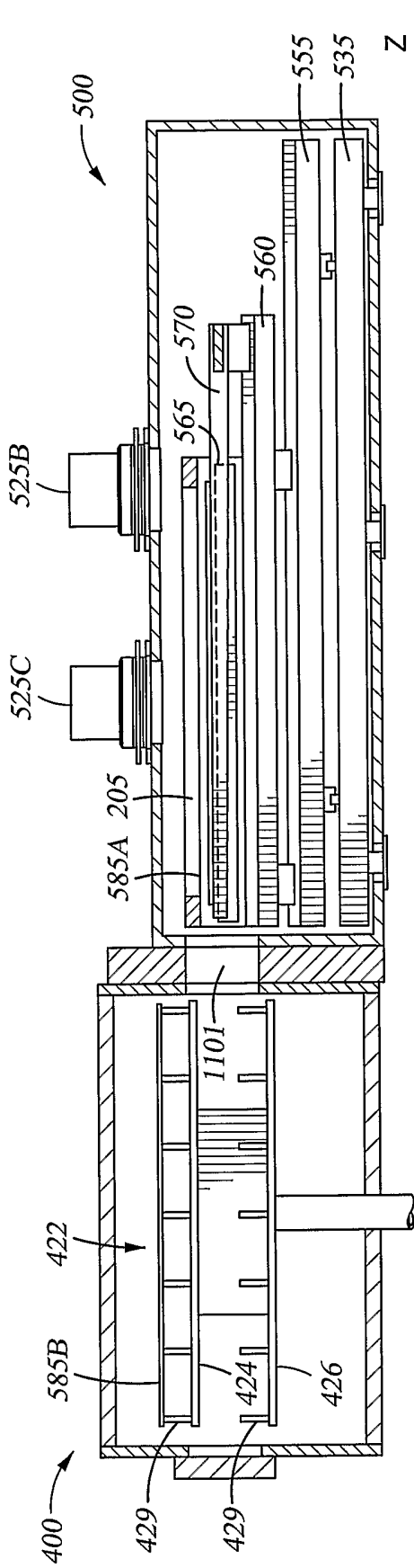


Fig. 13

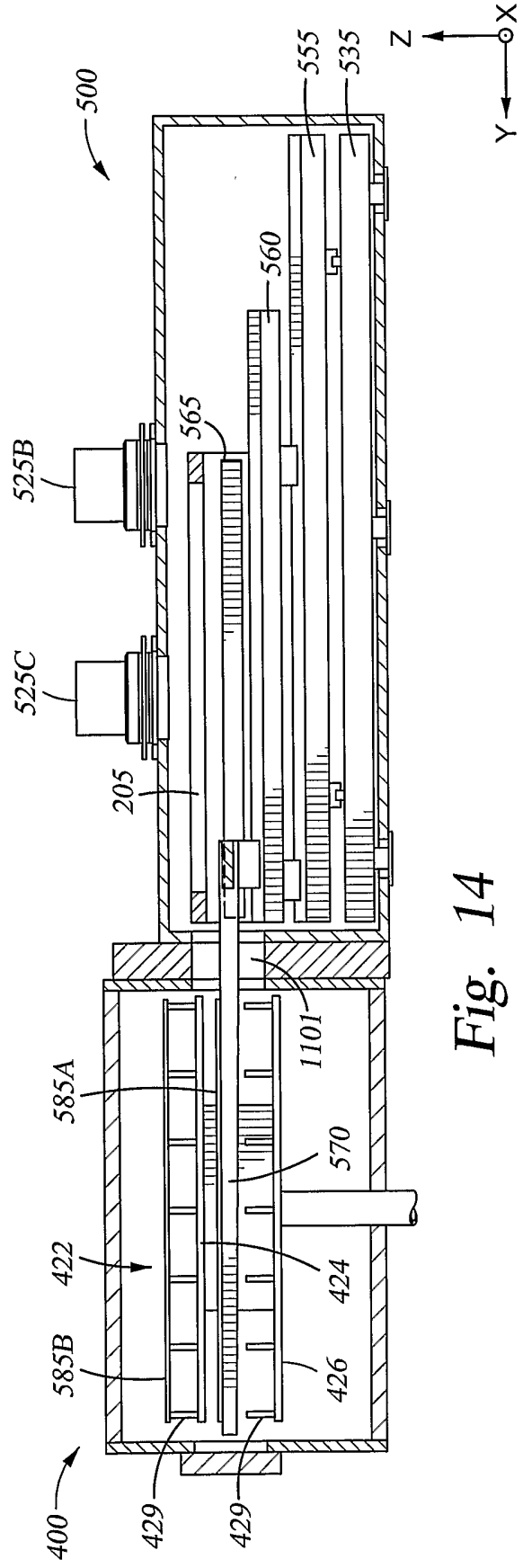


Fig. 14

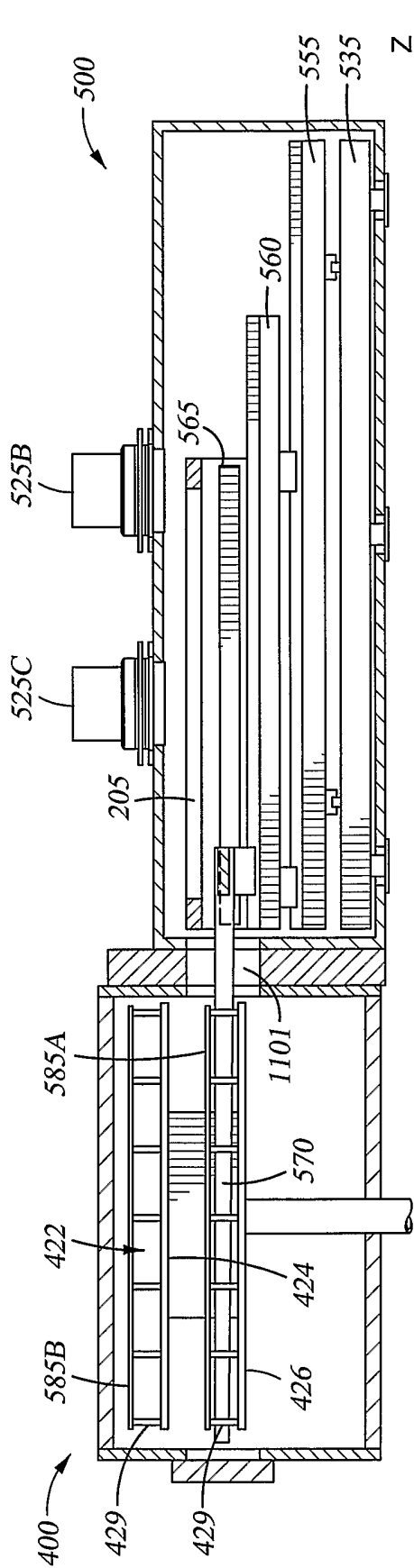


Fig. 15

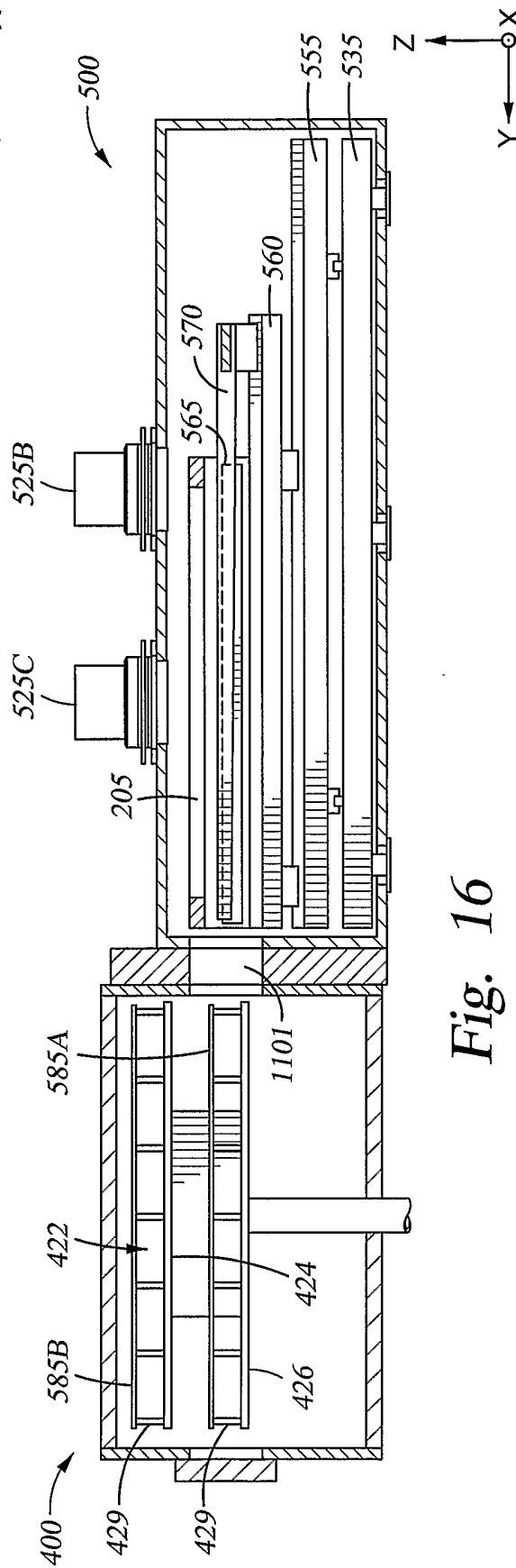


Fig. 16

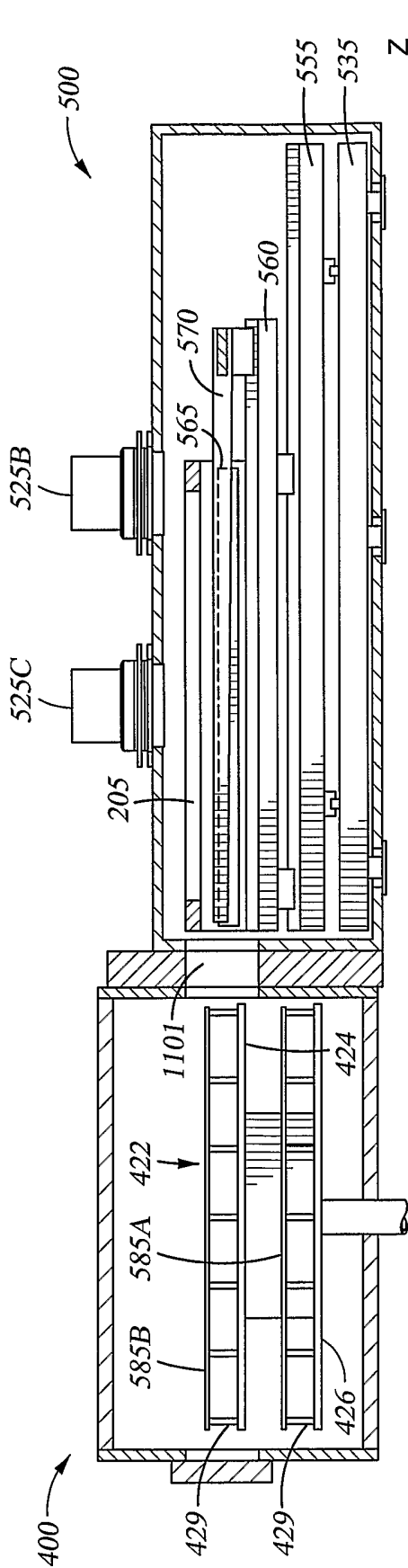


Fig. 17

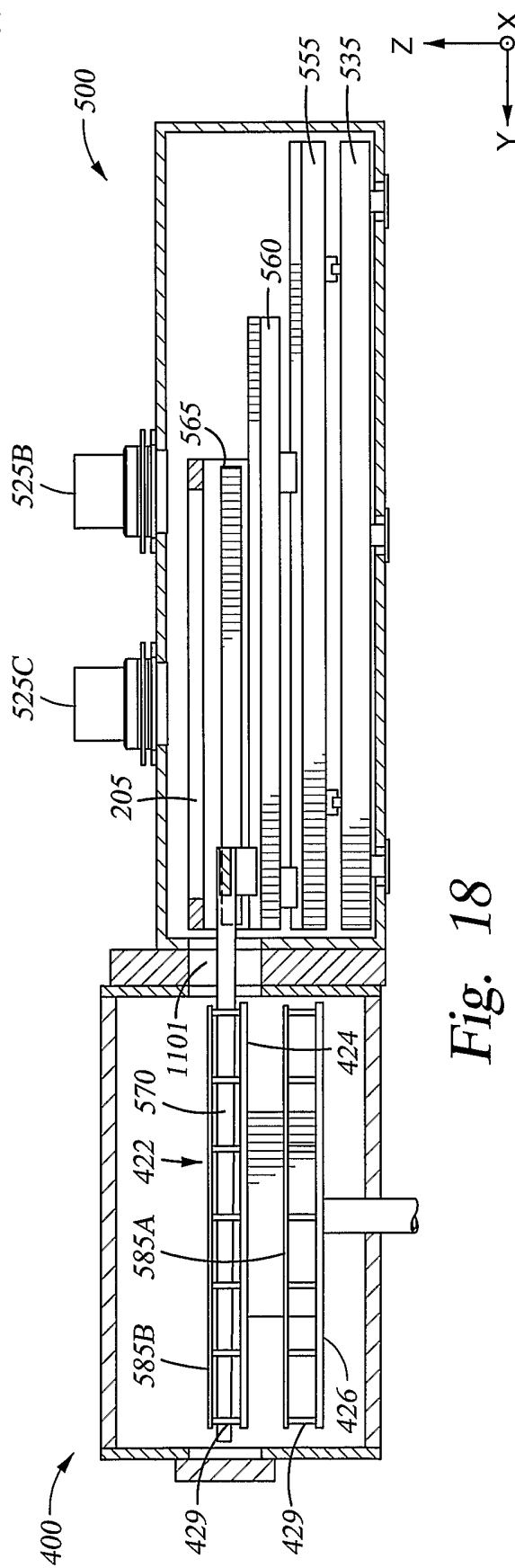


Fig. 18

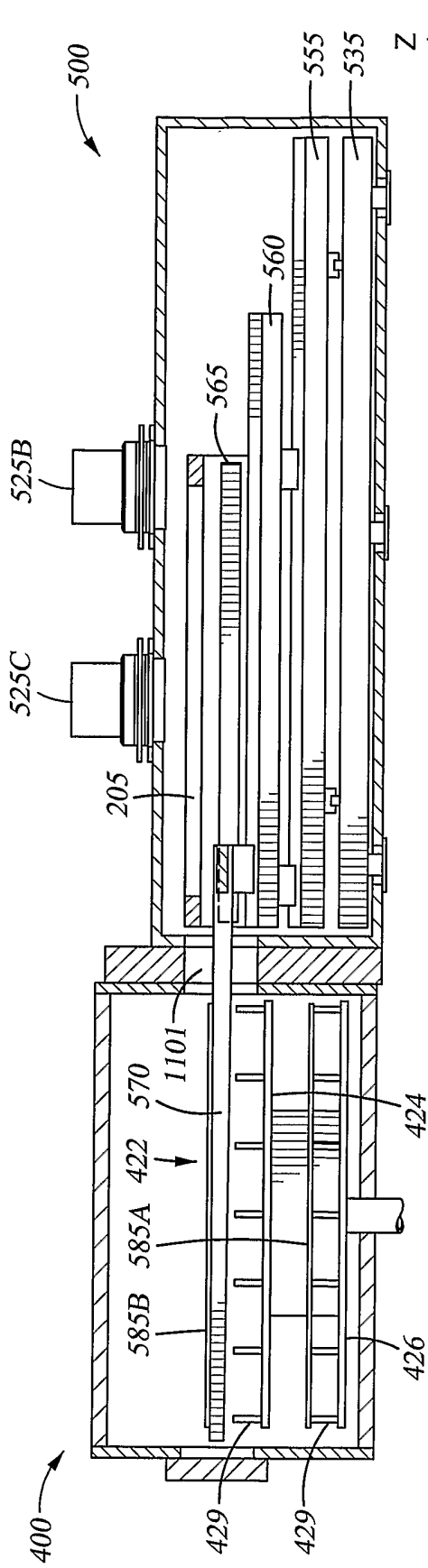


Fig. 19

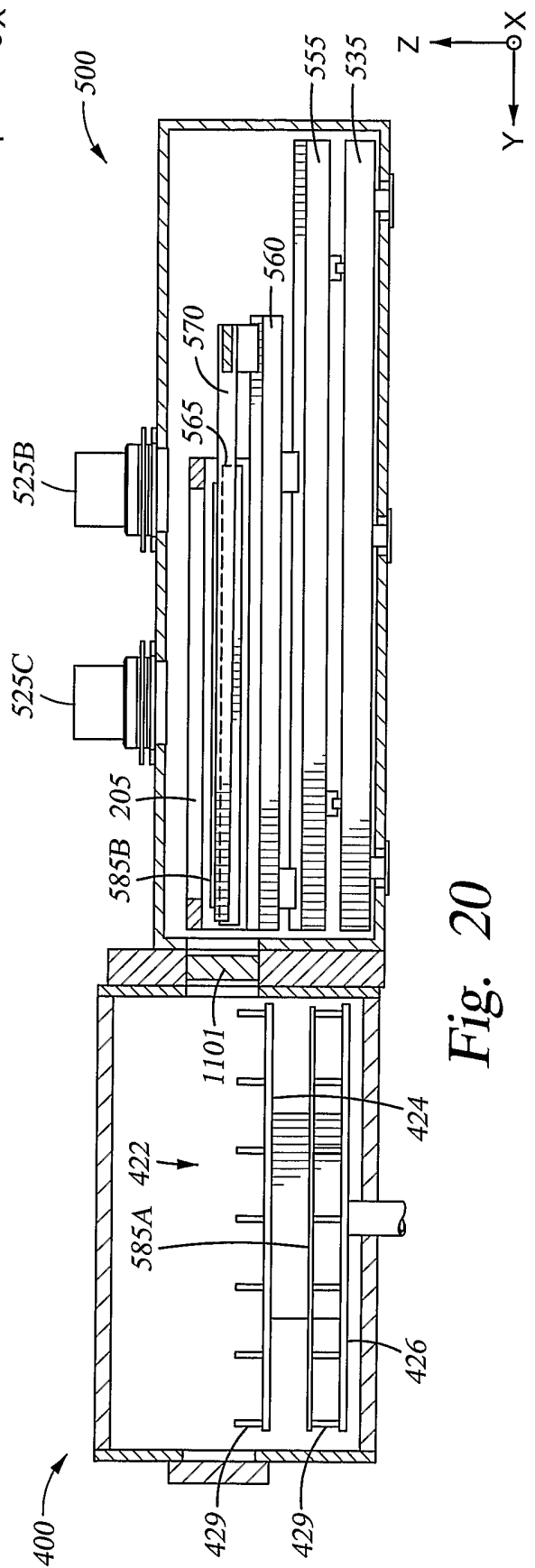


Fig. 20

INTERNATIONAL SEARCH REPORT

International Application No
PCT/US2004/043202

A. CLASSIFICATION OF SUBJECT MATTER
IPC 7 H01L21/00 G01R31/26 G09G3/00

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
IPC 7 H01L G01R G09G

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

EPO-Internal, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category °	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	WO 02/45137 A (TOKYO ELECTRON LIMITED; TOKYO ELECTRON ARIZONA, INC; COOMER, STEPHEN,) 6 June 2002 (2002-06-06) figure 4 the whole document -----	1-16

Further documents are listed in the continuation of box C.

Patent family members are listed in annex.

° Special categories of cited documents :

- "A" document defining the general state of the art which is not considered to be of particular relevance
- "E" earlier document but published on or after the international filing date
- "L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)
- "O" document referring to an oral disclosure, use, exhibition or other means
- "P" document published prior to the international filing date but later than the priority date claimed

- "T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
- "X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone
- "Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art.
- "&" document member of the same patent family

Date of the actual completion of the international search

27 April 2005

Date of mailing of the international search report

28. 07. 2005

Name and mailing address of the ISA

European Patent Office, P.B. 5818 Patentlaan 2
NL - 2280 HV Rijswijk
Tel. (+31-70) 340-2040, Tx. 31 651 epo nl,
Fax: (+31-70) 340-3016

Authorized officer

Bader, K

INTERNATIONAL SEARCH REPORT

International application No.
PCT/US2004/043202

Box II Observations where certain claims were found unsearchable (Continuation of item 2 of first sheet)

This International Search Report has not been established in respect of certain claims under Article 17(2)(a) for the following reasons:

1. Claims Nos.:
because they relate to subject matter not required to be searched by this Authority, namely:

2. Claims Nos.:
because they relate to parts of the International Application that do not comply with the prescribed requirements to such an extent that no meaningful International Search can be carried out, specifically:

3. Claims Nos.:
because they are dependent claims and are not drafted in accordance with the second and third sentences of Rule 6.4(a).

Box III Observations where unity of invention is lacking (Continuation of item 3 of first sheet)

This International Searching Authority found multiple inventions in this international application, as follows:

see additional sheet

1. As all required additional search fees were timely paid by the applicant, this International Search Report covers all searchable claims.

2. As all searchable claims could be searched without effort justifying an additional fee, this Authority did not invite payment of any additional fee.

3. As only some of the required additional search fees were timely paid by the applicant, this International Search Report covers only those claims for which fees were paid, specifically claims Nos.:

4. No required additional search fees were timely paid by the applicant. Consequently, this International Search Report is restricted to the invention first mentioned in the claims; it is covered by claims Nos.:

1-17

Remark on Protest

- The additional search fees were accompanied by the applicant's protest.
- No protest accompanied the payment of additional search fees.

FURTHER INFORMATION CONTINUED FROM PCT/ISA/ 210

This International Searching Authority found multiple (groups of) inventions in this international application, as follows:

1. claims: 1-17

A substrate table

2. claims: 18-26

A prober assembly

INTERNATIONAL SEARCH REPORT

Information on patent family members

International Application No

PCT/US2004/043202

Patent document cited in search report	Publication date	Patent family member(s)	Publication date	
WO 0245137	A	06-06-2002	US 2002064450 A1	30-05-2002
			AU 3680102 A	11-06-2002
			CN 1481577 A	10-03-2004
			EP 1340246 A2	03-09-2003
			JP 2004515073 T	20-05-2004
			TW 511136 B	21-11-2002
			WO 0245137 A2	06-06-2002
